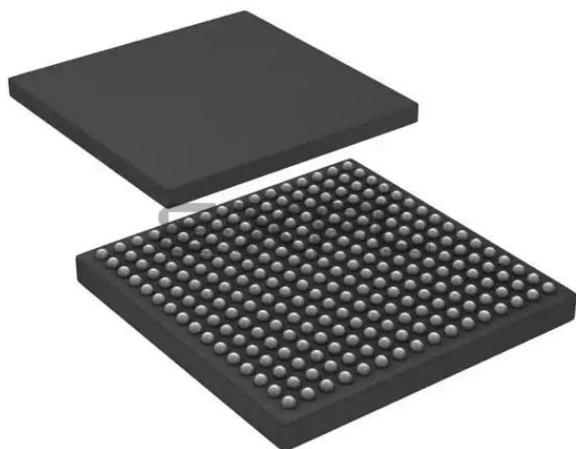




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What is "[Embedded - Microcontrollers](#)"?

"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "[Embedded - Microcontrollers](#)"

Details

Product Status	Active
Core Processor	ARM® Cortex®-M3
Core Size	32-Bit Single-Core
Speed	180MHz
Connectivity	CANbus, EBI/EMI, Ethernet, I ² C, IrDA, Microwire, QEI, MMC/SD, SPI, SSI, SSP, UART/USART, USB
Peripherals	Brown-out Detect/Reset, DMA, I ² S, LCD, POR, PWM, WDT
Number of I/O	164
Program Memory Size	-
Program Memory Type	ROMless
EEPROM Size	-
RAM Size	200K x 8
Voltage - Supply (Vcc/Vdd)	2.2V ~ 3.6V
Data Converters	A/D 8x10b; D/A 1x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	256-LBGA
Supplier Device Package	256-LBGA (17x17)
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/lpc18s50fet256-551

- ◆ Up to 164 General-Purpose Input/Output (GPIO) pins with configurable pull-up/pull-down resistors.
- ◆ GPIO registers are located on the AHB for fast access. GPIO ports have DMA support.
- ◆ Up to eight GPIO pins can be selected from all GPIO pins as edge and level sensitive interrupt sources.
- ◆ Two GPIO group interrupt modules enable an interrupt based on a programmable pattern of input states of a group of GPIO pins.
- ◆ Four general-purpose timer/counters with capture and match capabilities.
- ◆ One motor control PWM for three-phase motor control.
- ◆ One Quadrature Encoder Interface (QEI).
- ◆ Repetitive Interrupt timer (RI timer).
- ◆ Windowed watchdog timer.
- ◆ Ultra-low power Real-Time Clock (RTC) on separate power domain with 256 bytes of battery powered backup registers.
- ◆ Alarm timer; can be battery powered.
- Analog peripherals:
 - ◆ One 10-bit DAC with DMA support and a data conversion rate of 400 kSamples/s.
 - ◆ Two 10-bit ADCs with DMA support and a data conversion rate of 400 kSamples/s. Up to eight input channels per ADC.
- Unique ID for each device.
- Power:
 - ◆ Single 3.3 V (2.2 V to 3.6 V) power supply with on-chip internal voltage regulator for the core supply and the RTC power domain.
 - ◆ RTC power domain can be powered separately by a 3 V battery supply.
 - ◆ Four reduced power modes: Sleep, Deep-sleep, Power-down, and Deep power-down.
 - ◆ Processor wake-up from Sleep mode via wake-up interrupts from various peripherals.
 - ◆ Wake-up from Deep-sleep, Power-down, and Deep power-down modes via external interrupts and interrupts generated by battery powered blocks in the RTC power domain.
 - ◆ Brownout detect with four separate thresholds for interrupt and forced reset.
 - ◆ Power-On Reset (POR).
- Available as 144-pin LQFP packages and as 256-pin, 180-pin, and 100-pin BGA packages.

3. Applications

- | | |
|---------------------------|-------------------------------|
| ■ Communication hubs | ■ Embedded audio applications |
| ■ Automotive aftermarket | ■ Industrial control |
| ■ Power management | ■ Industrial automation |
| ■ Consumer health devices | ■ white goods |

6. Pinning information

6.1 Pinning

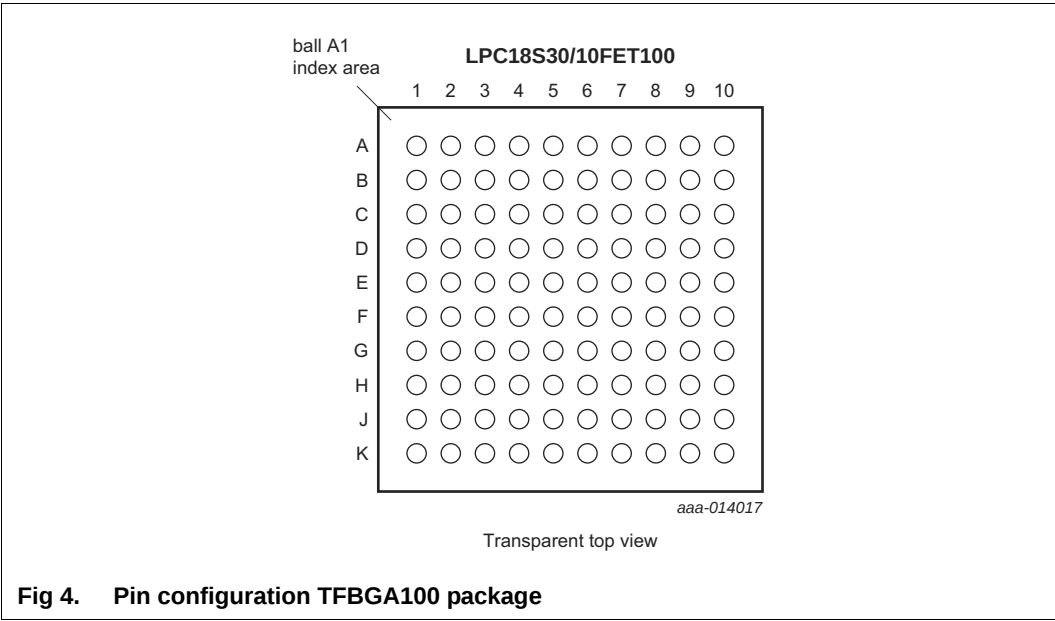
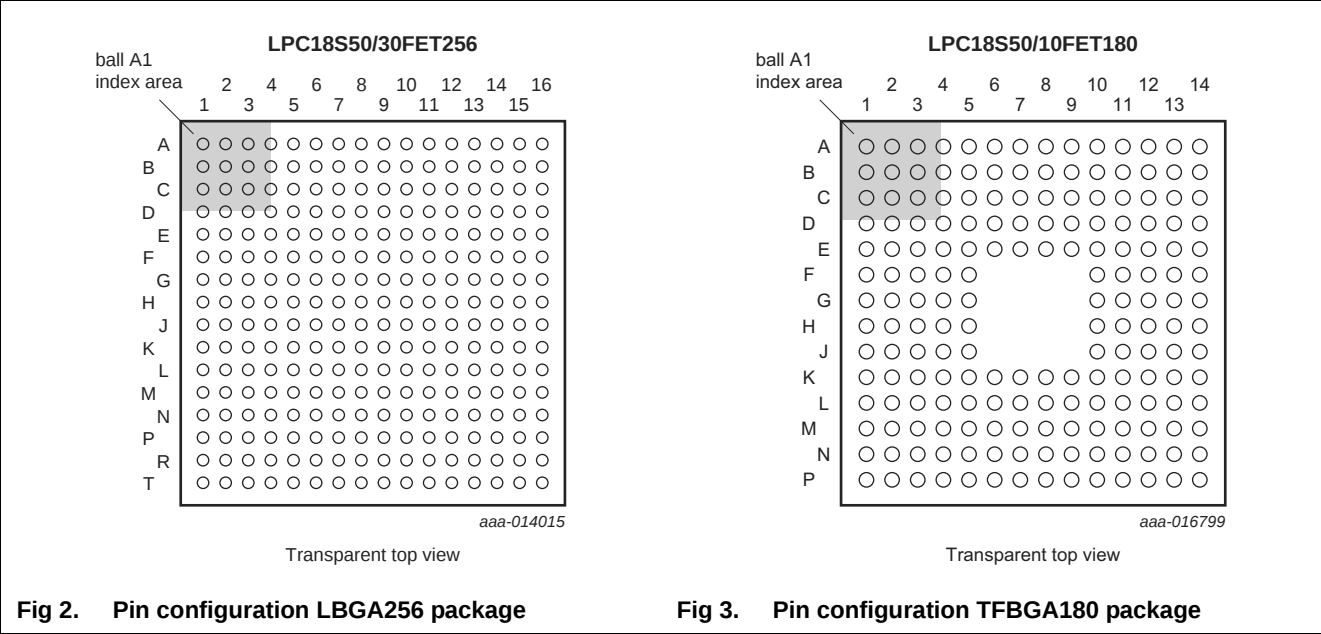


Table 3. Pin description ...continuedLCD, Ethernet, USB0, and USB1 functions are not available on all parts. See [Table 2](#).

Symbol	LBGA256	TFBGA180	TFBGA100	LQFP144		Reset state [1]	Type	Description
P1_20	M10	J10	K10	70	[2]	N; PU	I/O	GPIO0[15] — General purpose digital input/output pin.
							I/O	SSP1_SSEL — Slave Select for SSP1.
							-	R — Function reserved.
							O	ENET_TXD1 — Ethernet transmit data 1 (RMII/MII interface).
							I	T0_CAP2 — Capture input 2 of timer 0.
							-	R — Function reserved.
							-	R — Function reserved.
							-	R — Function reserved.
P2_0	T16	N14	G10	75	[2]	N; PU	-	R — Function reserved.
							O	U0_TXD — Transmitter output for USART0.
							I/O	EMC_A13 — External memory address line 13.
							O	USB0_PPWR — VBUS drive signal (towards external charge pump or power management unit); indicates that VBUS must be driven (active high). Add a pull-down resistor to disable the power switch at reset. This signal has opposite polarity compared to the USB_PPWR used on other NXP LPC parts.
							I/O	GPIO5[0] — General purpose digital input/output pin.
							-	R — Function reserved.
							I	T3_CAP0 — Capture input 0 of timer 3.
							O	ENET_MDC — Ethernet MIIM clock.
P2_1	N15	M13	G7	81	[2]	N; PU	-	R — Function reserved.
							I	U0_RXD — Receiver input for USART0.
							I/O	EMC_A12 — External memory address line 12.
							I	USB0_PWR_FAULT — Port power fault signal indicating overcurrent condition; this signal monitors over-current on the USB bus (external circuitry required to detect over-current condition).
							I/O	GPIO5[1] — General purpose digital input/output pin.
							-	R — Function reserved.
							I	T3_CAP1 — Capture input 1 of timer 3.
							-	R — Function reserved.

Table 3. Pin description ...continuedLCD, Ethernet, USB0, and USB1 functions are not available on all parts. See [Table 2](#).

Symbol	LBGA256	TFBGA180	TFBGA100	LQFP144		Reset state [1]	Type	Description
P3_1	G11	D10	F7	114	[2]	N; PU	I/O	I2S0_TX_WS — Transmit Word Select. It is driven by the master and received by the slave. Corresponds to the signal WS in the <i>I²S-bus specification</i> .
							I/O	I2S0_RX_WS — Receive Word Select. It is driven by the master and received by the slave. Corresponds to the signal WS in the <i>I²S-bus specification</i> .
							I	CAN0_RD — CAN receiver input.
							O	USB1_IND1 — USB1 Port indicator LED control output 1.
							I/O	GPIO5[8] — General purpose digital input/output pin.
							-	R — Function reserved.
							O	LCD_VD15 — LCD data.
P3_2	F11	D9	G6	116	[2]	OL; PU	-	R — Function reserved.
							I/O	I2S0_TX_SDA — I ² S transmit data. It is driven by the transmitter and read by the receiver. Corresponds to the signal SD in the <i>I²S-bus specification</i> .
							I/O	I2S0_RX_SDA — I ² S receive data. It is driven by the transmitter and read by the receiver. Corresponds to the signal SD in the <i>I²S-bus specification</i> .
							O	CAN0_TD — CAN transmitter output.
							O	USB1_IND0 — USB1 Port indicator LED control output 0.
							I/O	GPIO5[9] — General purpose digital input/output pin.
							-	R — Function reserved.
P3_3	B14	B13	A7	118	[4]	N; PU	O	LCD_VD14 — LCD data.
							-	R — Function reserved.
							-	R — Function reserved.
							I/O	SSP0_SCK — Serial clock for SSP0.
							O	SPIFI_SCK — Serial clock for SPIFI.
							O	CGU_OUT1 — CGU spare clock output 1.
							-	R — Function reserved.
							O	I2S0_TX_MCLK — I ² S transmit master clock.
							I/O	I2S1_TX_SCK — Transmit Clock. It is driven by the master and received by the slave. Corresponds to the signal SCK in the <i>I²S-bus specification</i> .

Table 3. Pin description ...continuedLCD, Ethernet, USB0, and USB1 functions are not available on all parts. See [Table 2](#).

Symbol	LBGA256	TFBGA180	TFBGA100	LQFP144		Reset state [1]	Type	Description
P7_1	C14	C13	-	113	[2]	N; PU	I/O	GPIO3[9] — General purpose digital input/output pin.
							O	CTOUT_15 — SCTimer/PWM output 15. Match output 3 of timer 3.
							I/O	I2S0_TX_WS — Transmit Word Select. It is driven by the master and received by the slave. Corresponds to the signal WS in the <i>I²S-bus specification</i> .
							O	LCD_VD19 — LCD data.
							O	LCD_VD7 — LCD data.
							-	R — Function reserved.
							O	U2_TXD — Transmitter output for USART2.
							-	R — Function reserved.
P7_2	A16	A14	-	115	[2]	N; PU	I/O	GPIO3[10] — General purpose digital input/output pin.
							I	CTIN_4 — SCTimer/PWM input 4. Capture input 2 of timer 1.
							I/O	I2S0_TX_SDA — I ² S transmit data. It is driven by the transmitter and read by the receiver. Corresponds to the signal SD in the <i>I²S-bus specification</i> .
							O	LCD_VD18 — LCD data.
							O	LCD_VD6 — LCD data.
							-	R — Function reserved.
							I	U2_RXD — Receiver input for USART2.
							-	R — Function reserved.
P7_3	C13	C12	-	117	[2]	N; PU	I/O	GPIO3[11] — General purpose digital input/output pin.
							I	CTIN_3 — SCTimer/PWM input 3. Capture input 1 of timer 1.
							-	R — Function reserved.
							O	LCD_VD17 — LCD data.
							O	LCD_VD5 — LCD data.
							-	R — Function reserved.
							-	R — Function reserved.
							-	R — Function reserved.

Table 3. Pin description ...continuedLCD, Ethernet, USB0, and USB1 functions are not available on all parts. See [Table 2](#).

Symbol	LBGA256	TFBGA180	TFBGA100	LQFP144		Reset state [1]	Type	Description
P8_7	K1	J1	-	-	[2]	N; PU	I/O	GPIO4[7] — General purpose digital input/output pin.
							O	USB1_ULPI_STP — ULPI link STP signal. Asserted to end or interrupt transfers to the PHY.
							-	R — Function reserved.
							O	LCD_VD4 — LCD data.
							O	LCD_PWR — LCD panel power enable.
							-	R — Function reserved.
							-	R — Function reserved.
							I	T0_CAP3 — Capture input 3 of timer 0.
P8_8	L1	K1	-	-	[2]	N; PU	-	R — Function reserved.
							I	USB1_ULPI_CLK — ULPI link CLK signal. 60 MHz clock generated by the PHY.
							-	R — Function reserved.
							-	R — Function reserved.
							-	R — Function reserved.
							-	R — Function reserved.
							O	CGU_OUT0 — CGU spare clock output 0.
							O	I2S1_TX_MCLK — I ² S1 transmit master clock.
P9_0	T1	P1	-	-	[2]	N; PU	I/O	GPIO4[12] — General purpose digital input/output pin.
							O	MCABORT — Motor control PWM, LOW-active fast abort.
							-	R — Function reserved.
							-	R — Function reserved.
							-	R — Function reserved.
							I	ENET_CRS — Ethernet Carrier Sense (MII interface).
							-	R — Function reserved.
							I/O	SSP0_SSEL — Slave Select for SSP0.
P9_1	N6	P4	-	-	[2]	N; PU	I/O	GPIO4[13] — General purpose digital input/output pin.
							O	MCOA2 — Motor control PWM channel 2, output A.
							-	R — Function reserved.
							-	R — Function reserved.
							I/O	I2S0_TX_WS — Transmit Word Select. It is driven by the master and received by the slave. Corresponds to the signal WS in the <i>I²S-bus specification</i> .
							I	ENET_RX_ER — Ethernet receive error (MII interface).
							-	R — Function reserved.
							I/O	SSP0_MISO — Master In Slave Out for SSP0.

Table 3. Pin description ...continuedLCD, Ethernet, USB0, and USB1 functions are not available on all parts. See [Table 2](#).

Symbol	LBGA256	TFBGA180	TFBGA100	LQFP144		Reset state [1]	Type	Description
P9_6	L11	M9	-	72	[2]	N; PU	I/O	GPIO4[11] — General purpose digital input/output pin.
							O	MCOB1 — Motor control PWM channel 1, output B.
							I	USB1_PWR_FAULT — USB1 Port power fault signal indicating over-current condition; this signal monitors over-current on the USB1 bus (external circuitry required to detect over-current condition).
							-	R — Function reserved.
							-	R — Function reserved.
							I	ENET_COL — Ethernet Collision detect (MII interface).
							-	R — Function reserved.
							I	U0_RXD — Receiver input for USART0.
PA_0	L12	L10	-	-	[2]	N; PU	-	R — Function reserved.
							-	R — Function reserved.
							-	R — Function reserved.
							-	R — Function reserved.
							-	R — Function reserved.
							O	I2S1_RX_MCLK — I ² S1 receive master clock.
							O	CGU_OUT1 — CGU spare clock output 1.
PA_1	J14	H12	-	-	[3]	N; PU	I/O	GPIO4[8] — General purpose digital input/output pin.
							I	QEI_IDX — Quadrature Encoder Interface INDEX input.
							-	R — Function reserved.
							O	U2_TXD — Transmitter output for USART2.
							-	R — Function reserved.
							-	R — Function reserved.
							-	R — Function reserved.
							-	R — Function reserved.
PA_2	K15	J13	-	-	[3]	N; PU	I/O	GPIO4[9] — General purpose digital input/output pin.
							I	QEI_PHB — Quadrature Encoder Interface PHB input.
							-	R — Function reserved.
							I	U2_RXD — Receiver input for USART2.
							-	R — Function reserved.
							-	R — Function reserved.
							-	R — Function reserved.
							-	R — Function reserved.

Table 3. Pin description ...continuedLCD, Ethernet, USB0, and USB1 functions are not available on all parts. See [Table 2](#).

Symbol	LBGA256	TFBGA180	TFBGA100	LQFP144		Reset state [1]	Type	Description
PA_3	H11	E10	-	-	[3]	N; PU	I/O	GPIO4[10] — General purpose digital input/output pin.
							I	QEI_PHA — Quadrature Encoder Interface PHA input.
							-	R — Function reserved.
							-	R — Function reserved.
							-	R — Function reserved.
							-	R — Function reserved.
							-	R — Function reserved.
							-	R — Function reserved.
PA_4	G13	E12	-	-	[2]	N; PU	-	R — Function reserved.
							O	CTOUT_9 — SCTimer/PWM output 9. Match output 3 of timer 3.
							-	R — Function reserved.
							I/O	EMC_A23 — External memory address line 23.
							I/O	GPIO5[19] — General purpose digital input/output pin.
							-	R — Function reserved.
							-	R — Function reserved.
PB_0	B15	D14	-	-	[2]	N; PU	-	R — Function reserved.
							O	CTOUT_10 — SCTimer/PWM output 10. Match output 3 of timer 3.
							O	LCD_VD23 — LCD data.
							-	R — Function reserved.
							I/O	GPIO5[20] — General purpose digital input/output pin.
							-	R — Function reserved.
							-	R — Function reserved.
PB_1	A14	A13	-	-	[2]	N; PU	-	R — Function reserved.
							I	USB1_ULPI_DIR — ULPI link DIR signal. Controls the ULP data line direction.
							O	LCD_VD22 — LCD data.
							-	R — Function reserved.
							I/O	GPIO5[21] — General purpose digital input/output pin.
							O	CTOUT_6 — SCTimer/PWM output 6. Match output 2 of timer 1.
							-	R — Function reserved.
							-	R — Function reserved.

Table 3. Pin description ...continuedLCD, Ethernet, USB0, and USB1 functions are not available on all parts. See [Table 2](#).

Symbol	LBGA256	TFBGA180	TFBGA100	LQFP144		Reset state [1]	Type	Description
PC_3	F5	-	-	-	[5]	N; PU	I/O	USB1_ULPI_D5 — ULPI link bidirectional data line 5.
							-	R — Function reserved.
							O	U1_RTS — Request to Send output for UART1. Can also be configured to be an RS-485/EIA-485 output enable signal for UART1.
							O	ENET_TXD3 — Ethernet transmit data 3 (MII interface).
							I/O	GPIO6[2] — General purpose digital input/output pin.
							-	R — Function reserved.
							-	R — Function reserved.
							O	SD_VOLT1 — SD/MMC bus voltage select output 1.
PC_4	F4	-	-	-	[2]	N; PU	AI	ADC1_0 — ADC1 and ADC0, input channel shared with DAC output. Configure the pin as GPIO input and use the ADC function select register in the SCU to select the ADC.
							-	R — Function reserved.
							I/O	USB1_ULPI_D4 — ULPI link bidirectional data line 4.
							-	R — Function reserved.
								ENET_TX_EN — Ethernet transmit enable (RMII/MII interface).
							I/O	GPIO6[3] — General purpose digital input/output pin.
							-	R — Function reserved.
							I	T3_CAP1 — Capture input 1 of timer 3.
PC_5	G4	-	-	-	[2]	N; PU	I/O	SD_DAT0 — SD/MMC data bus line 0.
							-	R — Function reserved.
							I/O	USB1_ULPI_D3 — ULPI link bidirectional data line 3.
							-	R — Function reserved.
							O	ENET_TX_ER — Ethernet Transmit Error (MII interface).
							I/O	GPIO6[4] — General purpose digital input/output pin.
							-	R — Function reserved.
							I	T3_CAP2 — Capture input 2 of timer 3.
PC_6	H6	-	-	-	[2]	N; PU	I/O	SD_DAT1 — SD/MMC data bus line 1.
							-	R — Function reserved.
							I/O	USB1_ULPI_D2 — ULPI link bidirectional data line 2.
							-	R — Function reserved.
							I	ENET_RXD2 — Ethernet receive data 2 (MII interface).
							I/O	GPIO6[5] — General purpose digital input/output pin.
							-	R — Function reserved.
							I	T3_CAP3 — Capture input 3 of timer 3.
PC_6	H6	-	-	-	[2]	N; PU	I/O	SD_DAT2 — SD/MMC data bus line 2.
							I/O	SD_DAT2 — SD/MMC data bus line 2.

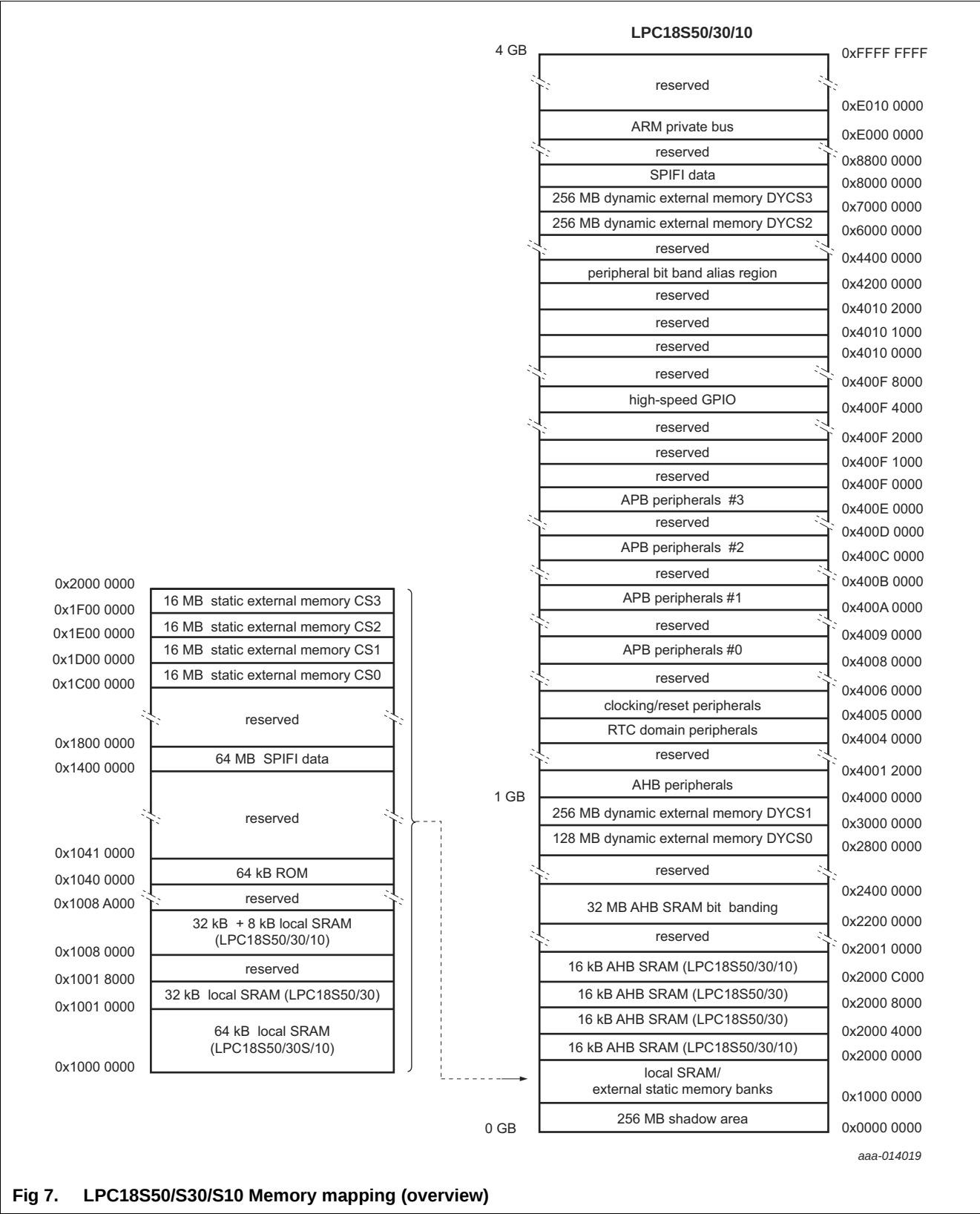
Table 3. Pin description ...continuedLCD, Ethernet, USB0, and USB1 functions are not available on all parts. See [Table 2](#).

Symbol	LBGA256	TFBGA180	TFBGA100	LQFP144		Reset state [1]	Type	Description
PD_4	T2	-	-	-	[2]	N; PU	-	R — Function reserved.
							O	CTOUT_8 — SCTimer/PWM output 8. Match output 0 of timer 2.
							I/O	EMC_D18 — External memory data line 18.
							-	R — Function reserved.
							I/O	GPIO6[18] — General purpose digital input/output pin.
							-	R — Function reserved.
							-	R — Function reserved.
PD_5	P6	-	-	-	[2]	N; PU	-	R — Function reserved.
							O	CTOUT_9 — SCTimer/PWM output 9. Match output 3 of timer 3.
							I/O	EMC_D19 — External memory data line 19.
							-	R — Function reserved.
							I/O	GPIO6[19] — General purpose digital input/output pin.
							-	R — Function reserved.
							-	R — Function reserved.
PD_6	R6	-	-	-	[2]	N; PU	-	R — Function reserved.
							O	CTOUT_10 — SCTimer/PWM output 10. Match output 3 of timer 3.
							I/O	EMC_D20 — External memory data line 20.
							-	R — Function reserved.
							I/O	GPIO6[20] — General purpose digital input/output pin.
							-	R — Function reserved.
							-	R — Function reserved.
PD_7	T6	-	-	-	[2]	N; PU	-	R — Function reserved.
							I	CTIN_5 — SCTimer/PWM input 5. Capture input 2 of timer 2.
							I/O	EMC_D21 — External memory data line 21.
							-	R — Function reserved.
							I/O	GPIO6[21] — General purpose digital input/output pin.
							-	R — Function reserved.
							-	R — Function reserved.

Table 3. Pin description ...continuedLCD, Ethernet, USB0, and USB1 functions are not available on all parts. See [Table 2](#).

Symbol	LBGA256	TFBGA180	TFBGA100	LQFP144		Reset state [1]	Type	Description
PD_12	N11	P9	-	-	[2]	N; PU	-	R — Function reserved.
							-	R — Function reserved.
							O	EMC_CS2 — LOW active Chip Select 2 signal.
							-	R — Function reserved.
							I/O	GPIO6[26] — General purpose digital input/output pin.
							-	R — Function reserved.
							O	CTOUT_10 — SCTimer/PWM output 10. Match output 3 of timer 3.
PD_13	T14	-	-	-	[2]	N; PU	-	R — Function reserved.
							I	CTIN_0 — SCTimer/PWM input 0. Capture input 0 of timer 0, 1, 2, 3.
							O	EMC_BLS2 — LOW active Byte Lane select signal 2.
							-	R — Function reserved.
							I/O	GPIO6[27] — General purpose digital input/output pin.
							-	R — Function reserved.
							O	CTOUT_13 — SCTimer/PWM output 13. Match output 3 of timer 3.
PD_14	R13	L11	-	-	[2]	N; PU	-	R — Function reserved.
							-	R — Function reserved.
							O	EMC_DYCS2 — SDRAM chip select 2.
							-	R — Function reserved.
							I/O	GPIO6[28] — General purpose digital input/output pin.
							-	R — Function reserved.
							O	CTOUT_11 — SCTimer/PWM output 11. Match output 3 of timer 2.
PD_15	T15	P13	-	-	[2]	N; PU	-	R — Function reserved.
							-	R — Function reserved.
							I/O	EMC_A17 — External memory address line 17.
							-	R — Function reserved.
							I/O	GPIO6[29] — General purpose digital input/output pin.
							I	SD_WP — SD/MMC card write protect input.
							O	CTOUT_8 — SCTimer/PWM output 8. Match output 0 of timer 2.
PD_15	T15	P13	-	-	[2]	N; PU	-	R — Function reserved.
							-	R — Function reserved.
							I/O	EMC_A17 — External memory address line 17.
							-	R — Function reserved.
							I/O	GPIO6[29] — General purpose digital input/output pin.
							I	SD_WP — SD/MMC card write protect input.
							O	CTOUT_8 — SCTimer/PWM output 8. Match output 0 of timer 2.
PD_15	T15	P13	-	-	[2]	N; PU	-	R — Function reserved.
							-	R — Function reserved.
							I/O	EMC_A17 — External memory address line 17.
							-	R — Function reserved.
							I/O	GPIO6[29] — General purpose digital input/output pin.
							I	SD_WP — SD/MMC card write protect input.
							O	CTOUT_8 — SCTimer/PWM output 8. Match output 0 of timer 2.
PD_15	T15	P13	-	-	[2]	N; PU	-	R — Function reserved.
							-	R — Function reserved.
							I/O	EMC_A17 — External memory address line 17.
							-	R — Function reserved.
							I/O	GPIO6[29] — General purpose digital input/output pin.
							I	SD_WP — SD/MMC card write protect input.
							O	CTOUT_8 — SCTimer/PWM output 8. Match output 0 of timer 2.

7.10 Memory mapping



10. Static characteristics

Table 10. Static characteristics

$T_{amb} = -40\text{ }^{\circ}\text{C}$ to $+85\text{ }^{\circ}\text{C}$ unless otherwise specified.

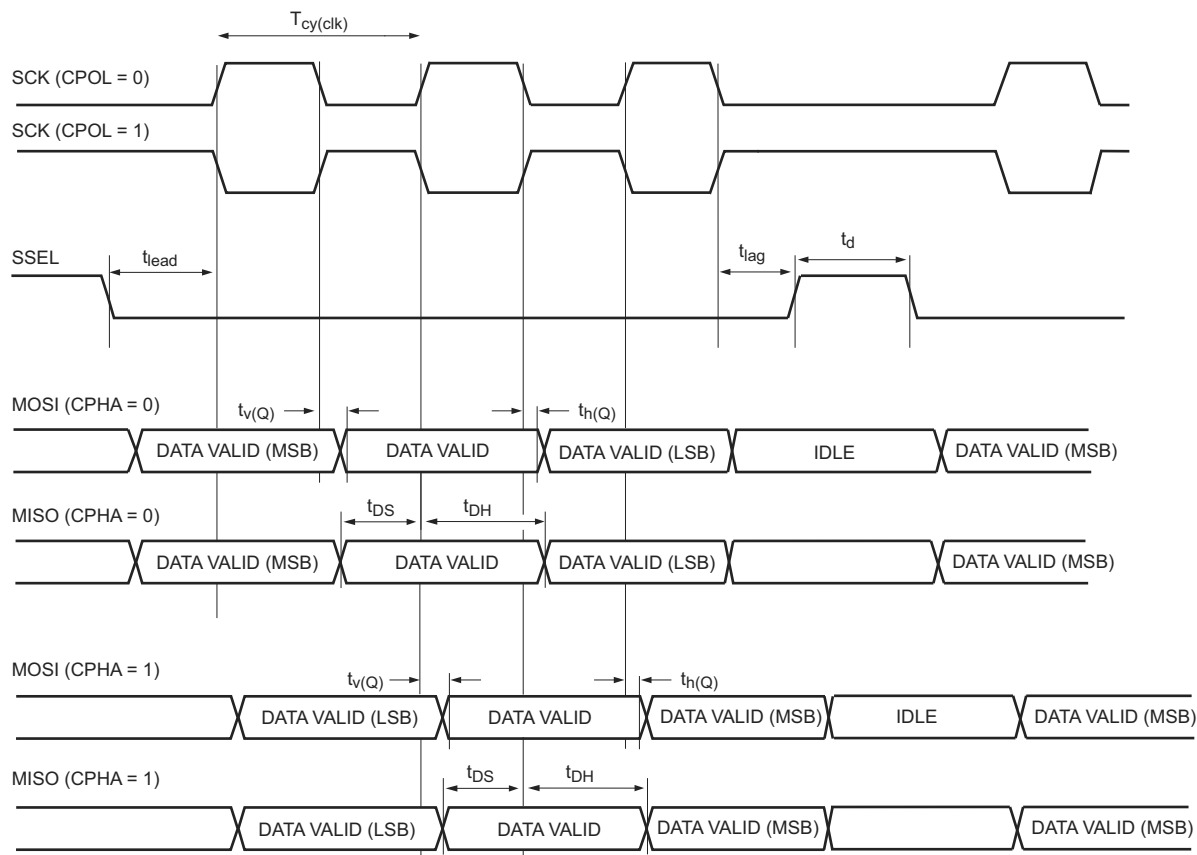
Symbol	Parameter	Conditions		Min	Typ ^[1]	Max	Unit
Supply pins							
$V_{DD(I/O)}$	input/output supply voltage			2.2	-	3.6	V
$V_{DD(REG)(3V3)}$	regulator supply voltage (3.3 V)		[2]	2.2	-	3.6	V
$V_{DDA(3V3)}$	analog supply voltage (3.3 V)	on pin VDDA		2.2	-	3.6	V
		on pins USB0_VDDA3V3_DRIVER and USB0_VDDA3V3		3.0	3.3	3.6	V
V_{BAT}	battery supply voltage		[2]	2.2	-	3.6	V
$V_{prog(pf)}$	polyfuse programming voltage	on pin VPP (for OTP)	[3]	2.7	-	3.6	V
$I_{prog(pf)}$	polyfuse programming current	on pin VPP; OTP programming time $\leq 1.6\text{ ms}$		-	-	30	mA
$I_{DD(REG)(3V3)}$	regulator supply current (3.3 V)	Active mode; code while(1){} executed from RAM; all peripherals disabled; PLL1 enabled					
		CCLK = 12 MHz	[4]	-	6.6	-	mA
		CCLK = 60 MHz	[4]		25.3	-	mA
		CCLK = 120 MHz	[4]	-	48.4	-	mA
		CCLK = 180 MHz	[4]	-	72.0	-	mA
$I_{DD(REG)(3V3)}$	regulator supply current (3.3 V)	after WFE/WFI instruction executed from RAM; all peripherals disabled					
		sleep mode	[4][5]	-	5.0	-	mA
		deep-sleep mode	[4]	-	30	-	μA
		power-down mode	[4]	-	15	-	μA
		deep power-down mode	[4][6]	-	0.03	-	μA
		deep power-down mode; VBAT floating	[4]	-	2	-	μA
I_{BAT}	battery supply current	active mode; $V_{BAT} = 3.2\text{ V}$; $V_{DD(REG)(3V3)} = 3.6\text{ V}$.	[7]	-	0	-	nA
I_{BAT}	battery supply current	$V_{DD(REG)(3V3)} = 3.3\text{ V}$; $V_{BAT} = 3.6\text{ V}$ deep-sleep mode	[9]	-	2	-	μA
		power-down mode	[9]	-	2	-	μA
		deep power-down mode	[9]	-	2	-	μA
				-	2	-	μA

- [5] PLL1 disabled; IRC running; CCLK = 12 MHz.
- [6] $V_{BAT} = 3.6\text{ V}$.
- [7] $V_{DD(I/O)} = V_{DDA} = 3.6\text{ V}$; over entire frequency range CCLK = 12 MHz to 180 MHz.
- [8] $V_{DD(REG)(3V3)} = 3.3\text{ V}$; $V_{DD(I/O)} = 3.3\text{ V}$. Input leakage increases when $V_{DD(I/O)}$ is floating or grounded. It is recommended to keep $V_{DD(REG)(3V3)}$ and $V_{DD(I/O)}$ powered in deep power-down mode.
- [9] On pin VBAT; $T_{amb} = 25\text{ }^{\circ}\text{C}$.
- [10] V_{ps} corresponds to the output of the power switch (see [Figure 9](#)) which is determined by the greater of V_{BAT} and $V_{DD(REG)(3V3)}$.
- [11] $V_{DDA(3V3)} = 3.3\text{ V}$; $T_{amb} = 25\text{ }^{\circ}\text{C}$.
- [12] Allowed as long as the current limit does not exceed the maximum current allowed by the device.
- [13] To V_{SS} .
- [14] The values specified are simulated and absolute values.
- [15] The weak pull-up resistor is connected to the $V_{DD(I/O)}$ rail and pulls up the I/O pin to the $V_{DD(I/O)}$ level.
- [16] The input cell disables the weak pull-up resistor when the applied input voltage exceeds $V_{DD(I/O)}$.
- [17] The parameter value specified is a simulated value excluding bond capacitance.
- [18] For USB operation $3.0\text{ V} \leq V_{DD(I/O)} \leq 3.6\text{ V}$. Guaranteed by design.
- [19] $V_{DD(I/O)}$ present.
- [20] Includes external resistors of $33\text{ }\Omega \pm 1\text{ }\%$ on D+ and D-.

Table 23. Dynamic characteristics: SSP pins in SPI mode

$T_{amb} = -40\text{ }^{\circ}\text{C}$ to $+85\text{ }^{\circ}\text{C}$; $2.2\text{ V} \leq V_{DD(REG)(3V3)} \leq 3.6\text{ V}$; $2.7\text{ V} \leq V_{DD(IO)} \leq 3.6\text{ V}$; $C_L = 20\text{ pF}$. Sampled at 10 % and 90 % of the signal level; EHS = 1 for all pins. Simulated values.

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
t _d	delay time	continuous transfer mode SPI mode; CPOL = 0; CPHA = 0		-	0.5 × T _{cy(clk)}	-	ns
		SPI mode; CPOL = 0; CPHA = 1		-	n/a	-	ns
		SPI mode; CPOL = 1; CPHA = 0		-	0.5 × T _{cy(clk)}	-	ns
		SPI mode; CPOL = 1; CPHA = 1		-	n/a	-	ns
		synchronous serial frame mode		-	T _{cy(clk)}	-	ns
		microwire frame format		-	n/a	-	ns
SSP slave							
PCLK	Peripheral clock frequency			-	-	180	MHz
T _{cy(clk)}	clock cycle time		[2]	1/(11 × 10 ⁶)	-	-	s
t _{DS}	data set-up time	in SPI mode		1.15	-	-	ns
t _{DH}	data hold time	in SPI mode		0.5	-	-	ns
t _{v(Q)}	data output valid time	in SPI mode		-	-	[4 × (1/PCLK)] + 3	ns
t _{h(Q)}	data output hold time	in SPI mode		5.1	-	-	ns
t _{lead}	lead time	continuous transfer mode SPI mode; CPOL = 0; CPHA = 0		T _{cy(clk)} + 2.2	-	-	ns
		SPI mode; CPOL = 0; CPHA = 1		0.5 × T _{cy(clk)} + 2.2	-	-	ns
		SPI mode; CPOL = 1; CPHA = 0		T _{cy(clk)} + 2.2	-	-	ns
		SPI mode; CPOL = 1; CPHA = 1		0.5 × T _{cy(clk)} + 2.2	-	-	ns
		synchronous serial frame mode		0.5 × T _{cy(clk)} + 2.2	-	-	ns
		microwire frame format		T _{cy(clk)} + 2.2	-	-	ns



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Fig 30. SSP master mode timing (SPI mode)

Table 25. Dynamic characteristics: Dynamic external memory interface

Simulated data over temperature and process range; $C_L = 10$ pF for $\overline{EMC_DYCSn}$, $\overline{EMC_RAS}$, $\overline{EMC_CAS}$, $\overline{EMC_WE}$, $\overline{EMC_An}$; $C_L = 9$ pF for $\overline{EMC_Dn}$; $C_L = 5$ pF for $\overline{EMC_DQMOUTn}$, $\overline{EMC_CLKn}$, $\overline{EMC_CKEOUTn}$; $T_{amb} = -40$ °C to 85 °C; $2.2\text{ V} \leq V_{DD(REG)(3V3)} \leq 3.6\text{ V}$; $V_{DD(IO)} = 3.3\text{ V} \pm 10\%$; $RD = 1$ (see LPC18xx User manual); $\overline{EMC_CLKn}$ delays $CLK0_DELAY = CLK1_DELAY = CLK2_DELAY = CLK3_DELAY = 0$.

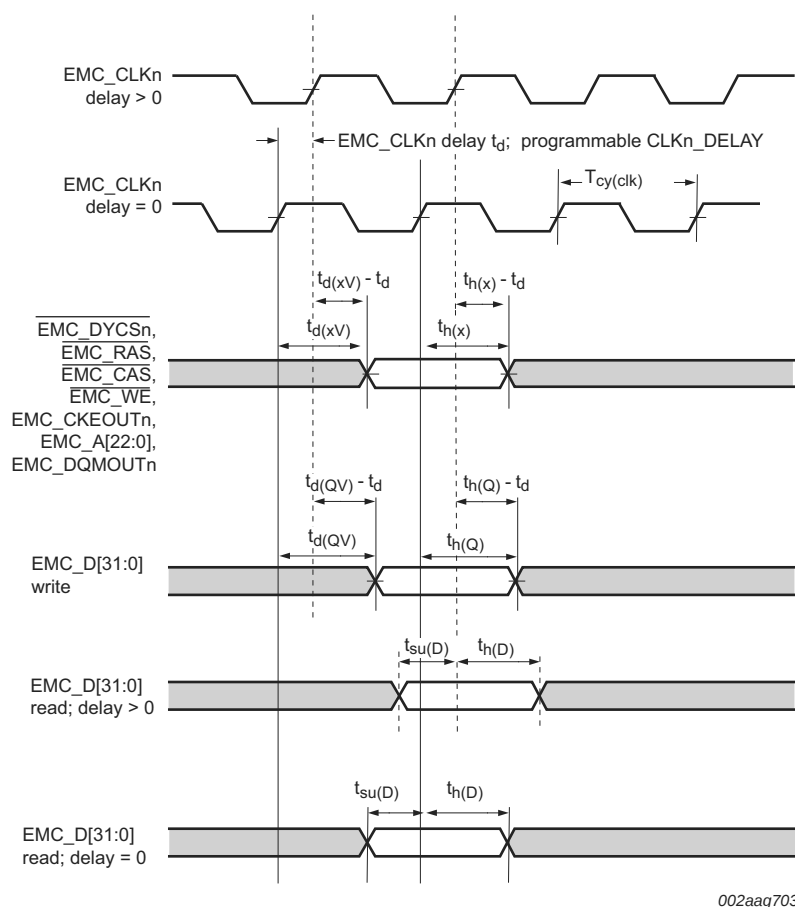
Symbol	Parameter	Min	Typ	Max	Unit
$T_{cy(clk)}$	clock cycle time	8.4	-	-	ns
Common to read and write cycles					
$t_{d(DYCSV)}$	DYCS delay time	-	$3.1 + 0.5 \times T_{cy(clk)}$	$5.1 + 0.5 \times T_{cy(clk)}$	ns
$t_{h(DYCS)}$	DYCS hold time	$0.3 + 0.5 \times T_{cy(clk)}$	$0.9 + 0.5 \times T_{cy(clk)}$	-	ns
$t_{d(RASV)}$	row address strobe valid delay time	-	$3.1 + 0.5 \times T_{cy(clk)}$	$4.9 + 0.5 \times T_{cy(clk)}$	ns
$t_{h(RAS)}$	row address strobe hold time	$0.5 + 0.5 \times T_{cy(clk)}$	$1.1 + 0.5 \times T_{cy(clk)}$	-	ns
$t_{d(CASV)}$	column address strobe valid delay time	-	$2.9 + 0.5 \times T_{cy(clk)}$	$4.6 + 0.5 \times T_{cy(clk)}$	ns
$t_{h(CAS)}$	column address strobe hold time	$0.3 + 0.5 \times T_{cy(clk)}$	$0.9 + 0.5 \times T_{cy(clk)}$	-	ns
$t_{d(WEV)}$	$\overline{WE}$ valid delay time	-	$3.2 + 0.5 \times T_{cy(clk)}$	$5.9 + 0.5 \times T_{cy(clk)}$	ns
$t_{h(WE)}$	$\overline{WE}$ hold time	$1.3 + 0.5 \times T_{cy(clk)}$	$1.4 + 0.5 \times T_{cy(clk)}$	-	ns
$t_{d(DQMOUTV)}$	DQMOUT valid delay time	-	$3.1 + 0.5 \times T_{cy(clk)}$	$5.0 + 0.5 \times T_{cy(clk)}$	ns
$t_{h(DQMOUT)}$	DQMOUT hold time	$0.2 + 0.5 \times T_{cy(clk)}$	$0.8 + 0.5 \times T_{cy(clk)}$	-	ns
$t_{d(AV)}$	address valid delay time	-	$3.8 + 0.5 \times T_{cy(clk)}$	$6.3 + 0.5 \times T_{cy(clk)}$	ns
$t_{h(A)}$	address hold time	$0.3 + 0.5 \times T_{cy(clk)}$	$0.9 + 0.5 \times T_{cy(clk)}$	-	ns
$t_{d(CKEOUTV)}$	CKEOUT valid delay time	-	$3.1 + 0.5 \times T_{cy(clk)}$	$5.1 + 0.5 \times T_{cy(clk)}$	ns
$t_{h(CKEOUT)}$	CKEOUT hold time	$0.5 \times T_{cy(clk)}$	$0.7 + 0.5 \times T_{cy(clk)}$	-	ns
Read cycle parameters					
$t_{su(D)}$	data input set-up time	-1.5	-0.5	-	ns
$t_{h(D)}$	data input hold time	2.2	0.8	-	ns
Write cycle parameters					
$t_{d(QV)}$	data output valid delay time	-	$3.8 + 0.5 \times T_{cy(clk)}$	$6.2 + 0.5 \times T_{cy(clk)}$	ns
$t_{h(Q)}$	data output hold time	$0.5 \times T_{cy(clk)}$	$0.7 + 0.5 \times T_{cy(clk)}$	-	ns

Table 26. Dynamic characteristics: Dynamic external memory interface; EMC_CLK[3:0] delay values

$T_{amb} = -40$ °C to 85 °C; $V_{DD(IO)} = 3.3\text{ V} \pm 10\%$; $2.2\text{ V} \leq V_{DD(REG)(3V3)} \leq 3.6\text{ V}$.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
t_d	delay time	delay value ^[1]				
		CLKn_DELAY = 0	0.0	0.0	0.0	ns
		CLKn_DELAY = 1 ^[1]	0.4	0.5	0.8	ns
		CLKn_DELAY = 2 ^[1]	0.7	1.0	1.7	ns
		CLKn_DELAY = 3 ^[1]	1.1	1.6	2.5	ns
		CLKn_DELAY = 4 ^[1]	1.4	2.0	3.3	ns
		CLKn_DELAY = 5 ^[1]	1.7	2.6	4.1	ns
		CLKn_DELAY = 6 ^[1]	2.1	3.1	4.9	ns
		CLKn_DELAY = 7 ^[1]	2.5	3.6	5.8	ns

[1] Program the EMC_CLKn delay values in the EMCDELAYCLK register (see the LPC18xx User manual). The delay values must be the same for all SDRAM clocks EMC_CLKn: $CLK0_DELAY = CLK1_DELAY = CLK2_DELAY = CLK3_DELAY$.



For the programmable EMC_CLK[3:0] clock delays CLK_n_DELAY, see [Table 26](#).

Remark: For SDRAM operation, set CLK₀_DELAY = CLK₁_DELAY = CLK₂_DELAY = CLK₃_DELAY in the EMCDELAYCLK register.

Fig 34. SDRAM timing

12. ADC/DAC electrical characteristics

Table 33. ADC characteristics

$V_{DDA(3V3)}$ over specified ranges; $T_{amb} = -40\text{ }^{\circ}\text{C}$ to $+85\text{ }^{\circ}\text{C}$; unless otherwise specified.

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
V_{IA}	analog input voltage			0	-	$V_{DDA(3V3)}$	V
C_{ia}	analog input capacitance			-	-	2	pF
E_D	differential linearity error	$2.7\text{ V} \leq V_{DDA(3V3)} \leq 3.6\text{ V}$	[1][2]	-	± 0.8	-	LSB
		$2.2\text{ V} \leq V_{DDA(3V3)} < 2.7\text{ V}$		-	± 1.0	-	LSB
$E_{L(adj)}$	integral non-linearity	$2.7\text{ V} \leq V_{DDA(3V3)} \leq 3.6\text{ V}$	[3]	-	± 0.8	-	LSB
		$2.2\text{ V} \leq V_{DDA(3V3)} < 2.7\text{ V}$		-	± 1.5	-	LSB
E_O	offset error	$2.7\text{ V} \leq V_{DDA(3V3)} \leq 3.6\text{ V}$	[4]	-	± 0.15	-	LSB
		$2.2\text{ V} \leq V_{DDA(3V3)} < 2.7\text{ V}$		-	± 0.15	-	LSB
E_G	gain error	$2.7\text{ V} \leq V_{DDA(3V3)} \leq 3.6\text{ V}$	[5]	-	± 0.3	-	%
		$2.2\text{ V} \leq V_{DDA(3V3)} < 2.7\text{ V}$		-	± 0.35	-	%
E_T	absolute error	$2.7\text{ V} \leq V_{DDA(3V3)} \leq 3.6\text{ V}$	[6]	-	± 3	-	LSB
		$2.2\text{ V} \leq V_{DDA(3V3)} < 2.7\text{ V}$		-	± 4	-	LSB
R_{vsi}	voltage source interface resistance	see Figure 40		-	-	$1/(7 \times f_{clk(ADC)} \times C_{ia})$	k Ω
R_i	input resistance		[7][8]	-	-	1.2	M Ω
$f_{clk(ADC)}$	ADC clock frequency			-	-	4.5	MHz
f_s	sampling frequency	10-bit resolution; 11 clock cycles		-	-	400	kSamples/s
		2-bit resolution; 3 clock cycles				1.5	MSamples/s

[1] The ADC is monotonic, there are no missing codes.

[2] The differential linearity error (E_D) is the difference between the actual step width and the ideal step width. See [Figure 39](#).

[3] The integral non-linearity ($E_{L(adj)}$) is the peak difference between the center of the steps of the actual and the ideal transfer curve after appropriate adjustment of gain and offset errors. See [Figure 39](#).

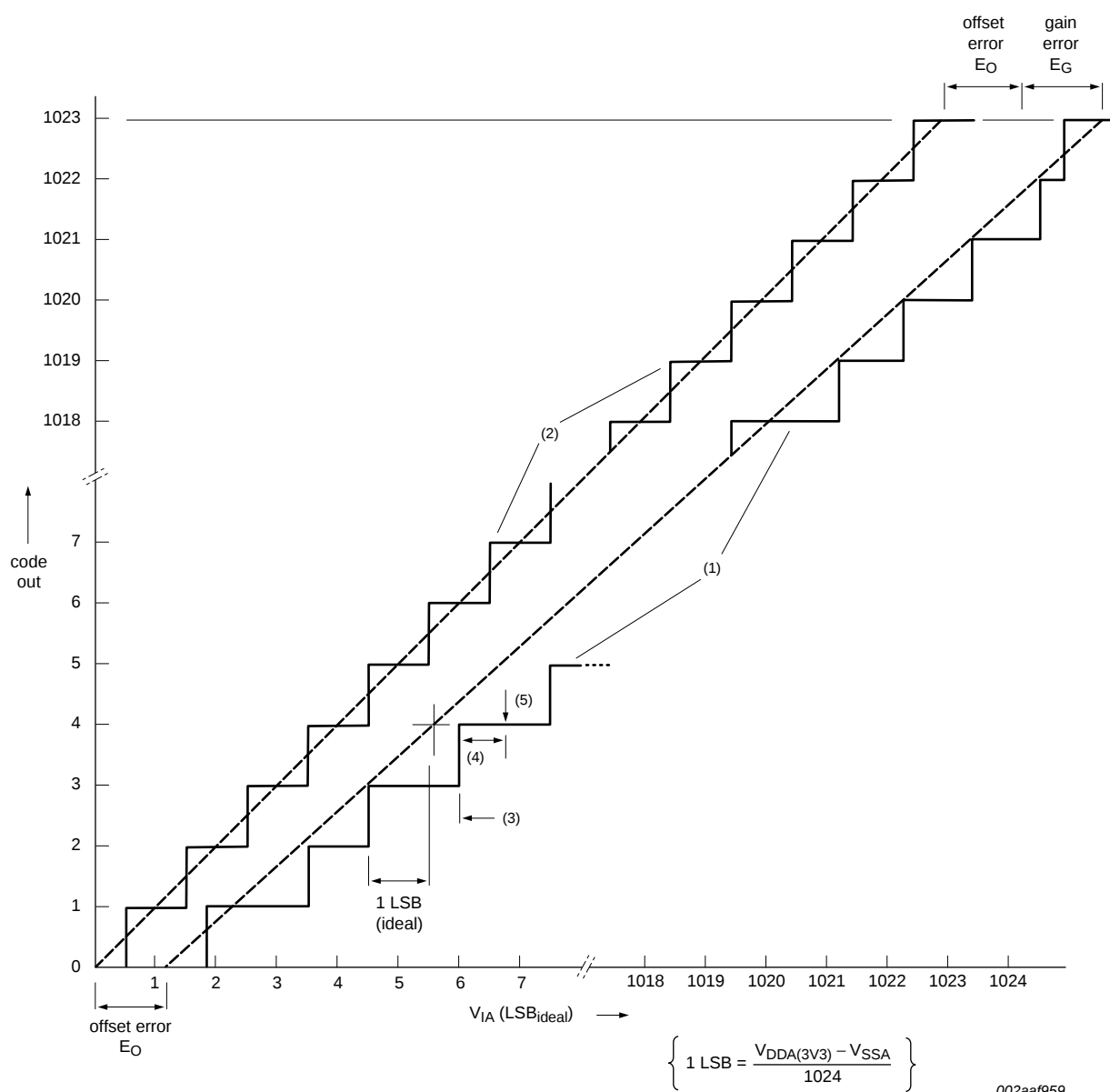
[4] The offset error (E_O) is the absolute difference between the straight line which fits the actual curve and the straight line which fits the ideal curve. See [Figure 39](#).

[5] The gain error (E_G) is the relative difference in percent between the straight line fitting the actual transfer curve after removing offset error, and the straight line which fits the ideal transfer curve. See [Figure 39](#).

[6] The absolute error (E_T) is the maximum difference between the center of the steps of the actual transfer curve of the non-calibrated ADC and the ideal transfer curve. See [Figure 39](#).

[7] $T_{amb} = 25\text{ }^{\circ}\text{C}$.

[8] Input resistance R_i depends on the sampling frequency f_s : $R_i = 2\text{ k}\Omega + 1 / (f_s \times C_{ia})$.



- (1) Example of an actual transfer curve.
- (2) The ideal transfer curve.
- (3) Differential linearity error (E_D).
- (4) Integral non-linearity ($E_{L(adj)}$).
- (5) Center of a step of the actual transfer curve.

Fig 39. 10-bit ADC characteristics